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**IN THE UNITED STATES PATENT AND
TRADEMARK OFFICE**

PATENT

Applicant(s): Misuo Sugiyama; Hatsuyuki Arai Docket No.: 30598.0004
Reissue of 5,605,499 Application No.: 08/421,706
Patent No.:
Issued: February 25, 1997 Filed: April 13, 1995
Title: FLATTENING METHOD AND Examiner: Andrew Weinberg
FLATTENING APPARATUS OF A SEMICONDUCTOR DEVICE

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination of the captioned reissue application, please amend the application as follows:

In the Claims

Rewrite claim 1 as follows:

1. (Amended) A flattening method of a semiconductor device by a chemical-mechanical polishing process comprising,
preparing a synthetic resin polishing cloth in a circular form and a tool for forming a surface layer of the synthetic resin polishing cloth to have fluff thereon in a polishing process,
said tool having an annular shape with a diameter less than a radial length of the polishing cloth, and